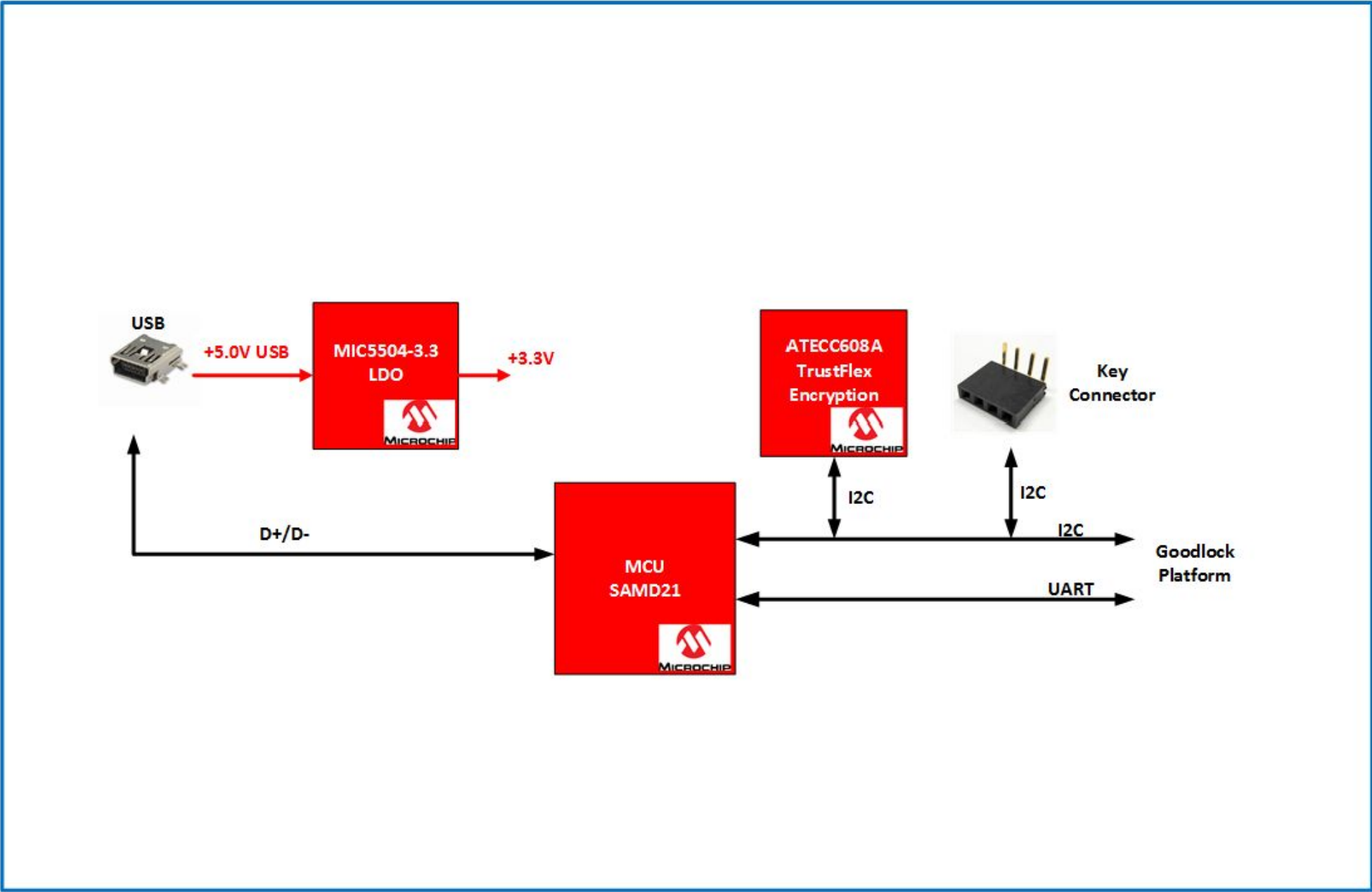


TrustFlexShield Rev 0



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THE FUTURE ELECTRONICS CORPORATION.

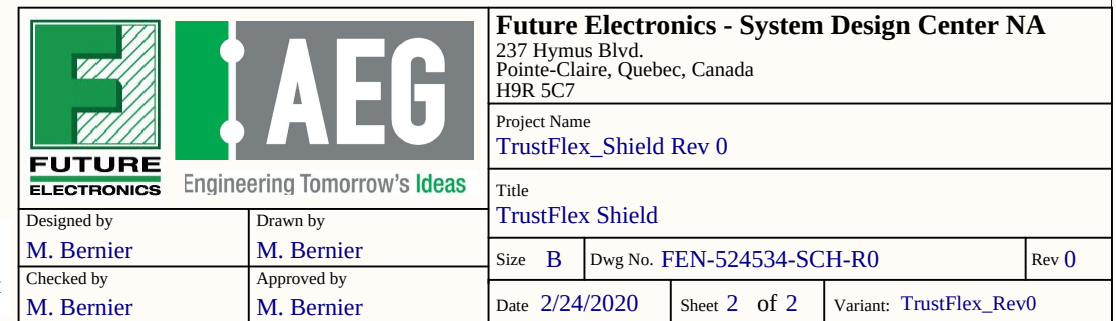
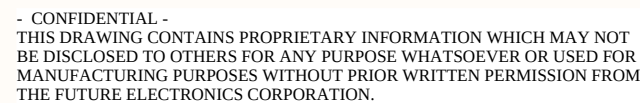
 Engineering Tomorrow's Ideas	
Designed by M. Bernier	Drawn by M. Bernier
Checked by M. Bernier	Approved by M. Bernier

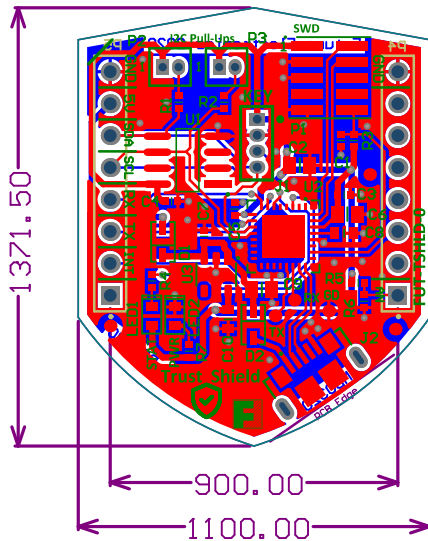
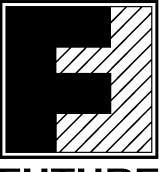
Future Electronics - System Design Center NA 237 Hymus Blvd. Pointe-Claire, Quebec, Canada H9R 5C7		
Project Name TrustFlex_Shield Rev 0		
Title Block Diagram		
Size B	Dwg No. FEN-524534-SCH-R0	Rev 0
Date 2/24/2020	Sheet 1 of 2	Variant: TrustFlex_Rev0

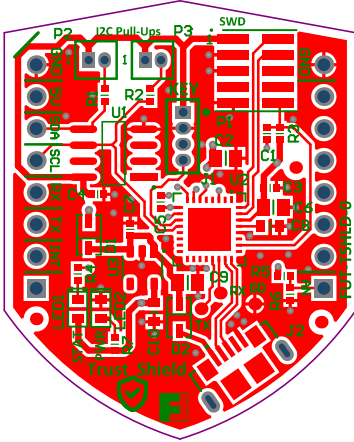
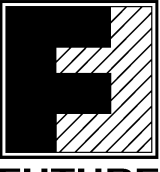
Wiring diagram for USB3076-30-A showing connections for J2:

- Pin 1: USB_IN
- Pin 2: USB_D N
- Pin 3: USB_D P
- Pin 4: Unconnected
- Pin 5: Unconnected
- Pin 6: GND

The diagram shows a 5V to 3.3V DC-DC converter. The input is labeled 'EXT 5V'. Two Schottky diodes, D1 and D2 (B0540WS-7), are connected in series. The output of the diodes is connected to the VIN pin of the MIC5504-3.3YM5-TR (U3). The EN pin is connected to GND. The VOUT pin is connected to the output of the converter, which is then connected to a 3.3V regulator (C10, 4u7, 0603, 10V 10%) and a resistor R7 (330R). The output of the resistor is connected to an LED (LED2, SML-LX0603GW-TR). The ground connection is labeled 'GND'.

[illegible][illegible]

1	2	3	4	5	6	7	8																																																																								
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Layers

Bottom Layer

Impedance Requirements

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3. COPPER FOIL WEIGHT - SEE TABLE FOR STACK-UP DETAIL

4. PLATING - 0.5oz ☒ 0.75oz ☐ 1oz ☐ Other ☐ _____

5. FINISH - HASL RoHS ☒ HASL ☐ Immersion Silver ☐ Immersion Tin ☐ ENIG ☐
Other ☐ _____

6. SOLDER MASK - APPLY SOLDER MASK AS PER SPECIFIED IPC-SM-840 ON PCB OVER BARE COPPER

- GREEN ☐ WHITE ☐ BLUE ☐ Other ☒ BLACK

7. SILKSCREEN - LPI - APPLY EPOXY BASED INK

- TOP/BOTTOM ☒ TOP ONLY ☐ BOTTOM ONLY ☐ NONE ☐

- WHITE ☒ BLACK ☐ Other ☐ _____

8. IMPEDANCE CONTROL - NO ☒ YES ☐ SEE TABLE FOR DETAIL

9. ELECTRICAL TEST - 100% IPC-D-356B

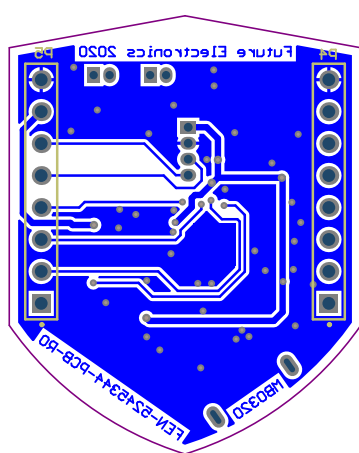
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TO DIMENSION SHOWN



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Future Electronics – System Design Center NA
237 Hymus Blvd
Pointe-Claire, Quebec, Canada
H9R 5C7

Project #	TrustFlex Shield Rev0
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Title:	TrustFlex Shield board
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Size: B	DWG NO: FEN-524534-PCB-RC
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Date: 2/24/2020

Sheet 1 of 1

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